

# SOT2041-1

WLCSP4, wafer level chip scale package, 4 terminals; 0.6 mm pitch; 1.015 mm x 1.015 mm x 0.38 mm body (backside coating included)

18 November 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP4
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	09-08-2019
<b>Manufacturer package code</b>	98ASA01499D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.995	1.015	1.035	mm
package width	0.995	1.015	1.035	mm
package height	-	0.38	0.41	mm
ball diameter	0.19	0.21	0.23	mm
ball height	0.115	0.13	0.145	mm
die thickness with BSP	0.225	0.25	0.275	mm
nominal pitch	-	0.6	-	mm
actual quantity of termination	-	4	-	



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2 Package outline

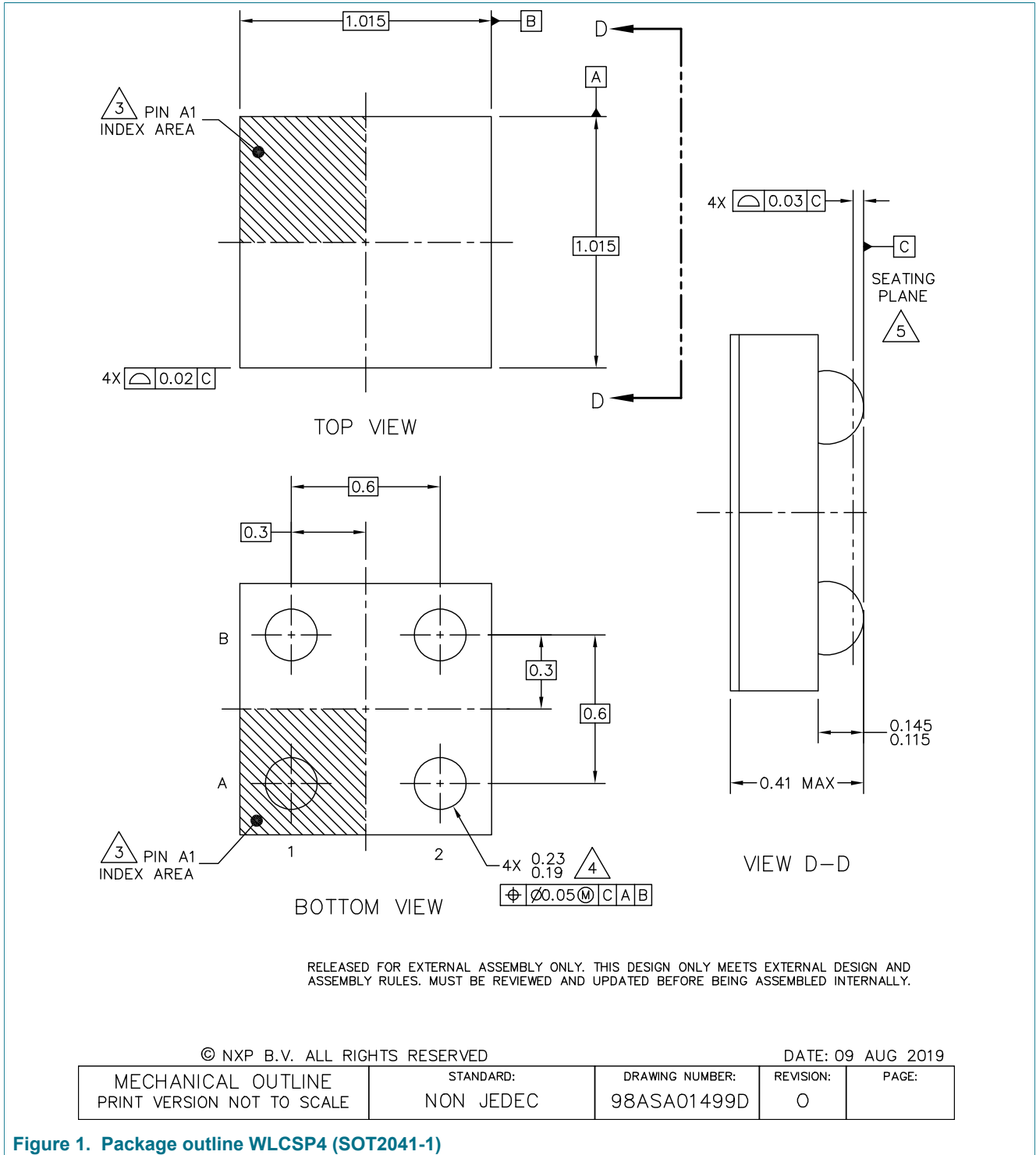


Figure 1. Package outline WLCSP4 (SOT2041-1)

WLCSP4, wafer level chip scale package, 4 terminals; 0.6 mm pitch; 1.015 mm x 1.015 mm x 0.38 mm body (backside coating included)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

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DATE: 09 AUG 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01499D	REVISION: 0	PAGE:
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Figure 2. Package outline note WLCSP4 (SOT2041-1)

WLCSP4, wafer level chip scale package, 4 terminals; 0.6 mm pitch; 1.015 mm x 1.015 mm x 0.38 mm body (backside coating included)

### 3 Legal information

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